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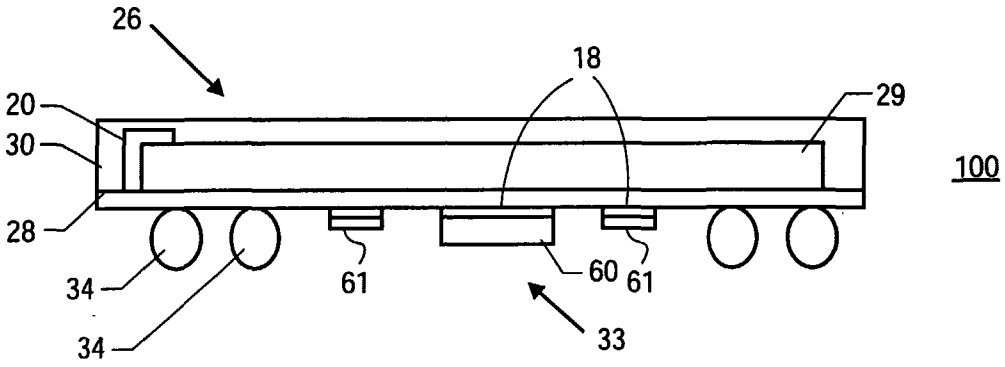
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(54) Title: PACKAGE FOR A NON-VOLATILE MEMORY DEVICE INCLUDING INTEGRATED PASSIVE DEVICES AND METHOD FOR MAKING THE SAME



(57) Abstract: In accordance with one embodiment of the invention, a memory device package includes an integrated circuit die having a memory array and at least one passive component mounted to a substrate. In alternative embodiments, an array of solder balls may be mounted around the passive component.

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